

SECTION A-A
SCALE 4 : 1

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA484T1.0C-DC229AD	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA484T1.0-DC229AD	Sn63/Pb37	Sn63	NO	YES

- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.63 mm (25 MIL).
 - 4) SOLDER MASK DEFINED PAD SRO 0.508 mm (20 MIL).
 - 5) PAD Cu DIAMETER: 0.635 mm (25 MIL).
 - 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) BALL PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

APPROVALS	DATE	TopLine®			
DRAWN T.Au	6/11/2021				
ENG M. Hart	6/11/2021	TITLE BGA484T1.0-DC229AD DAISY CHAIN			
MFG		SCALE 4:1	SIZE A	DRAWING NO. 512293	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



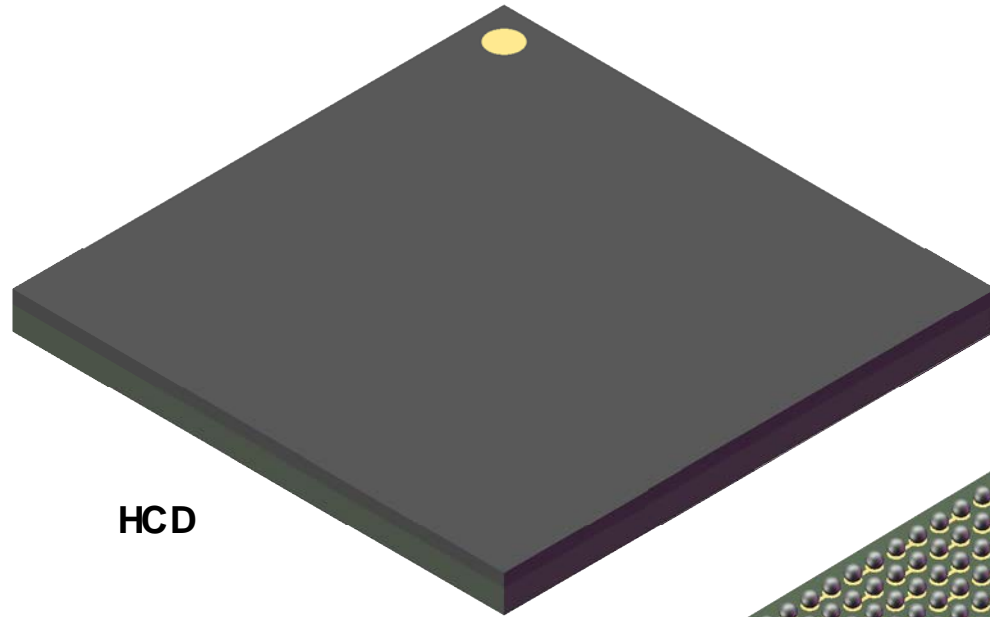
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.635 mm (25 MIL).
- 3) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508 mm (20 MIL).
- 4) PCB TRACING LINE WIDTH 0.152 mm [6 MIL].

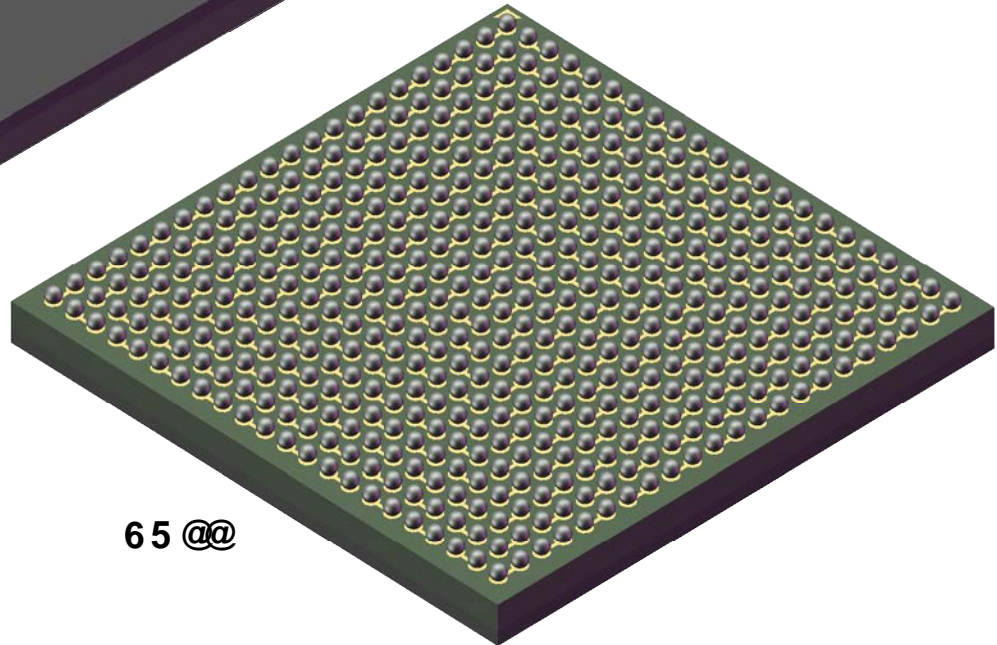
TopLine®

TITLE			
BGA484T1.0-DC229AD DAISY CHAIN			
SCALE	SIZE	DRAWING NO.	REV
5:1	A	512293	A
DO NOT SCALE DRAWING			SHEET 2 OF 4

AC89@
6; 5 'K #k '65 @@



HCD



65 @@

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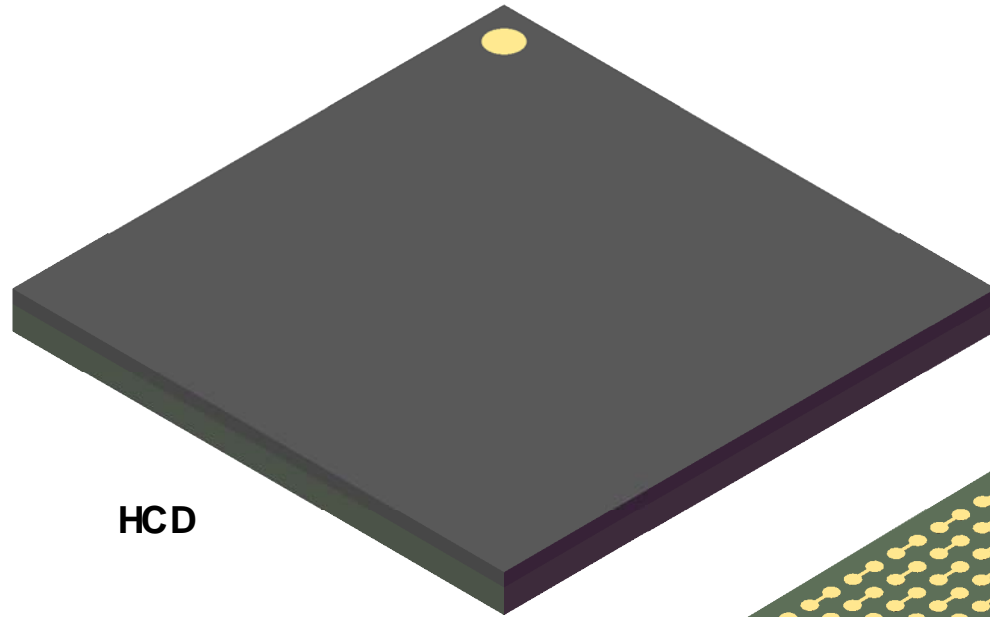
TITLE BGA484T1.0-DC229AD
DAISY CHAIN

SCALE 4:1	SIZE A	DRAWING NO. 512293	REV A
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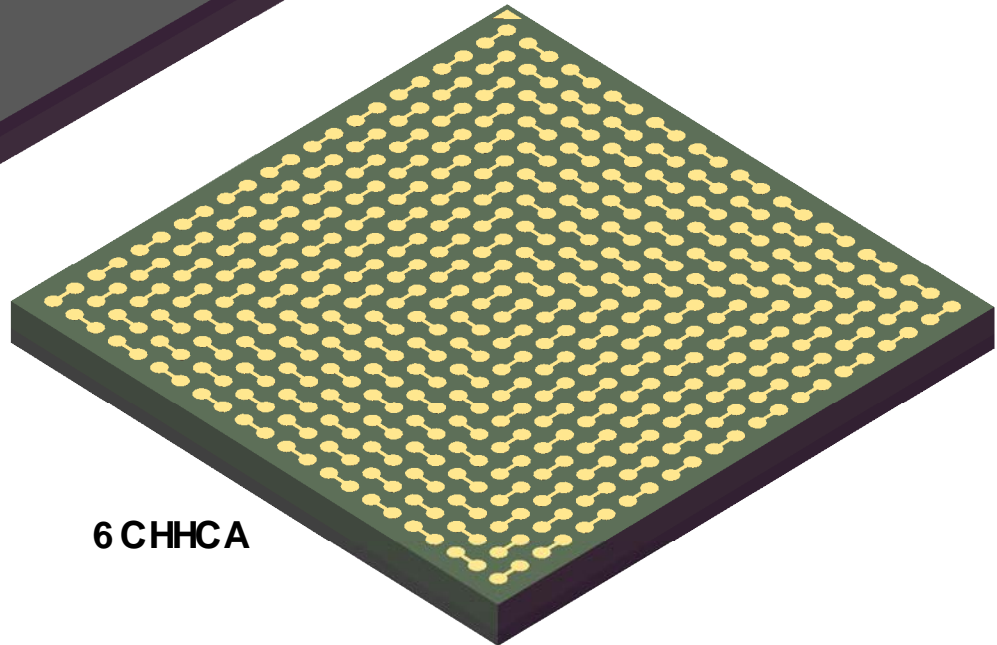
DO NOT SCALE DRAWING

SHEET 3 OF 4

AC89@
@ 5'K #<CI H'65 @@



HCD



6 CHHCA

TopLine[®]

TITLE BGA484T1.0-DC229AD
DAISY CHAIN

SCALE	SIZE	DRAWING NO.	REV
4:1	A	512293	A

DO NOT SCALE DRAWING

SHEET 4 OF 4